




MICROCHANNEL ARRAY

series: MCA



- Smaller, light weight solution with more efficient building block form factor compared to traditional heat sinks.
- Lowers cooling energy requirements.
- Can operate with conventional server fans or energy blowers.
- Integrated heat pipes enhance heat transfer performance.
- Eliminates need for liquid cooling.
- Scalable to replace heat sinks on any electronics.
- Typical applications include AI, crypto currency mining, CPU/GPU, mobile electronics, automotive and power supplies.

Examples of Microchannel Array Configurations

Item	MCA 1U 180 W	MCA 1U 300 W	MCA 2U 400 4
Supported TDP (watts)	180	300	400
Watts cooled per cm ²	31.57	31.57	48
Dimensions (mm)	30.6 x 29.9 x 39.2	50.1 x 32.34 x 39.3	50.5 x 38 x 88
			

Performance Comparison

Item	Conventional Heat sink	Microchannel Array 180W
Server Form (Factor)	2U	1U
Supported CPU SKU	AMD EPYC 7000 and 7002 Series Processors	
Supported CPU Socket	OLGA4094 (Socket SP3)	
Supported CPU TDP (Watts)	180	
Watts Cooled per cm ²	1.9	3.2
Weight (oz)	15.55	0.95
Dimensions (mm)	119.1 x 78.9 x 64.3	30.6 x 29.9 x 39.2
	